

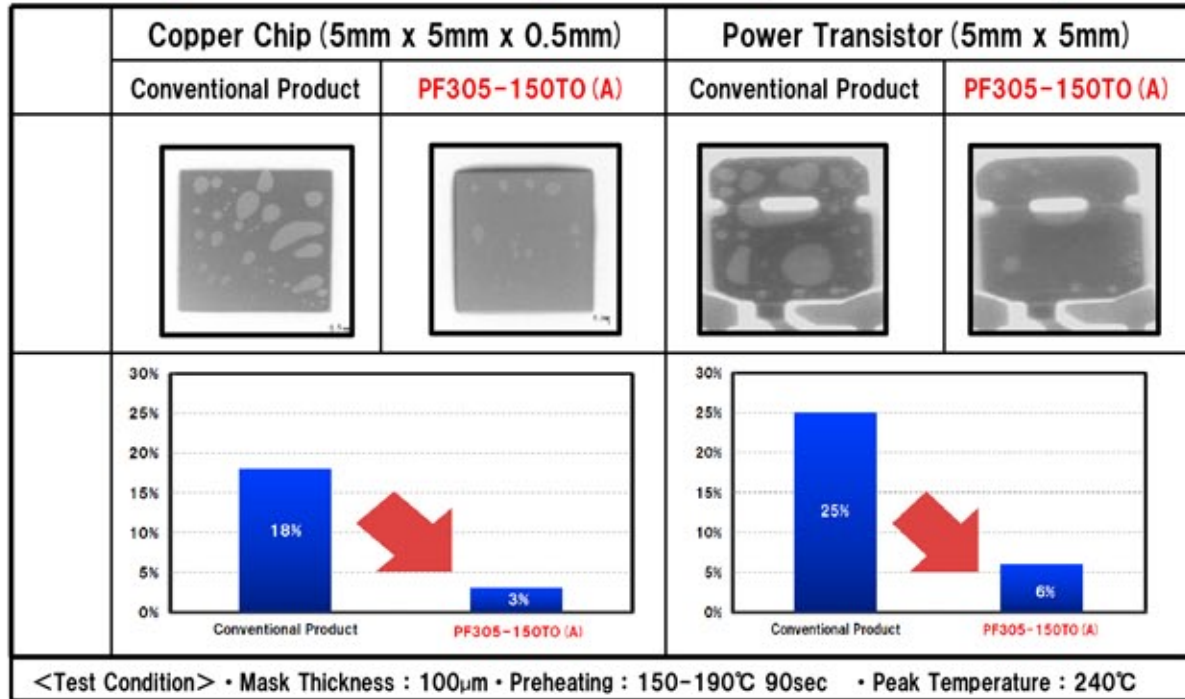
ROLO Pb-Free Solder Paste for SMT Reflow



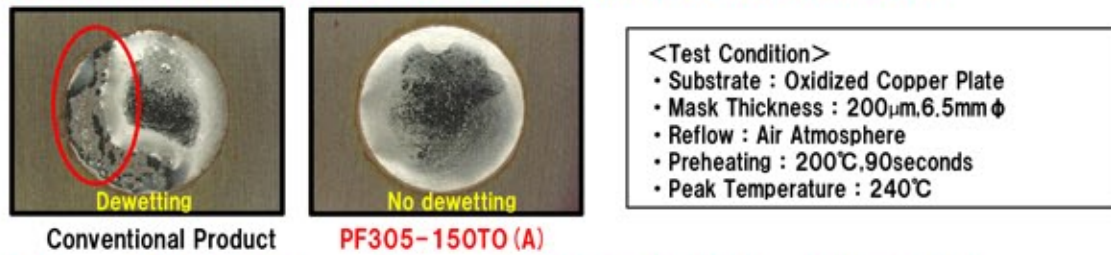
Less Voids even at Air Reflow

PF305-150TO(A)

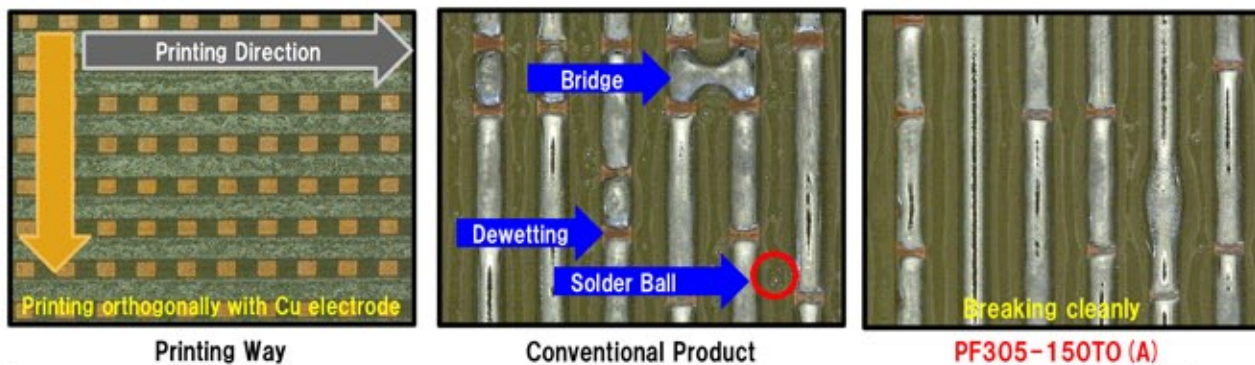
◆ Reducing Void Generation in Large Area Printing even at Air Atmosphere



◆ Good Wettability even on Oxidized Substrate at Air Reflow



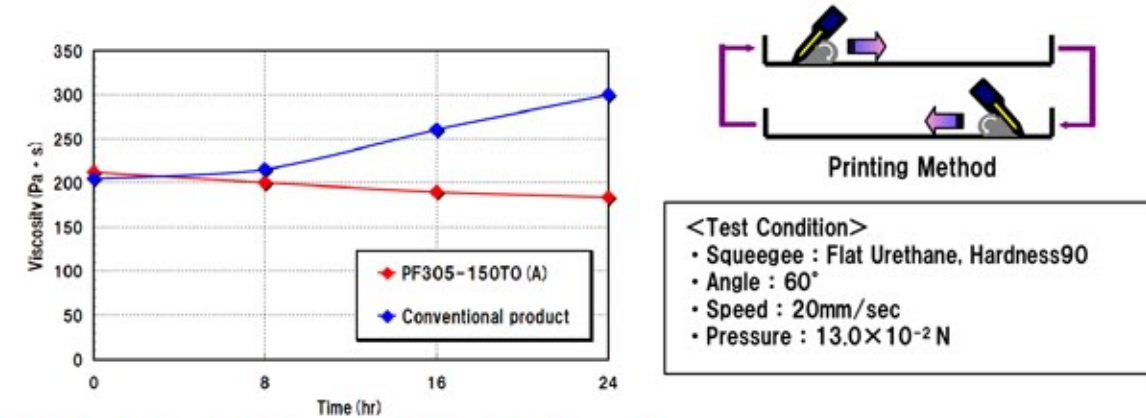
◆ Less Solder Bridge and Less Solder Ball with Good Wettability



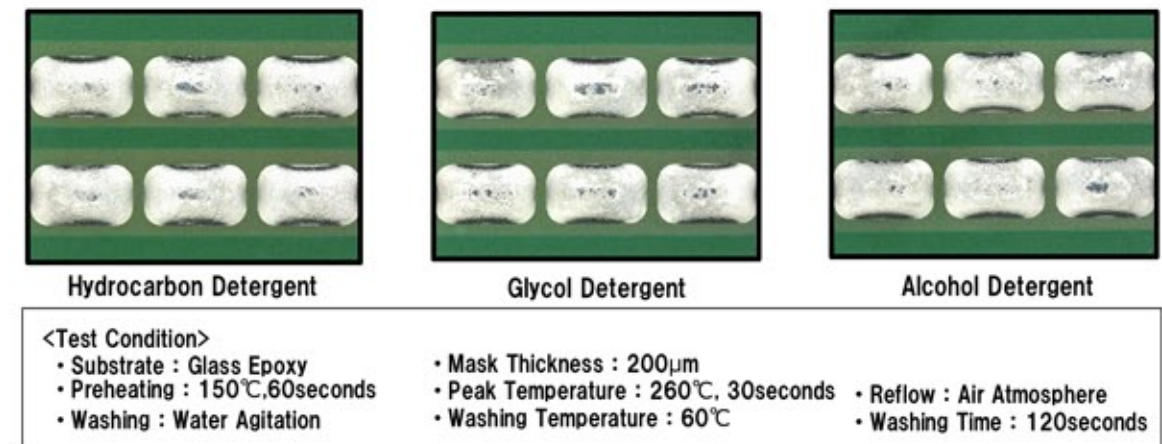
<Test Condition>

- Substrate : JIS II Interdigitated Alloy Electrode
- Mask Thickness : 100 μ m
- Reflow : Air Atmosphere
- Preheating : 150-190 $^{\circ}$ C, 90seconds
- Peak Temperature : 240 $^{\circ}$ C

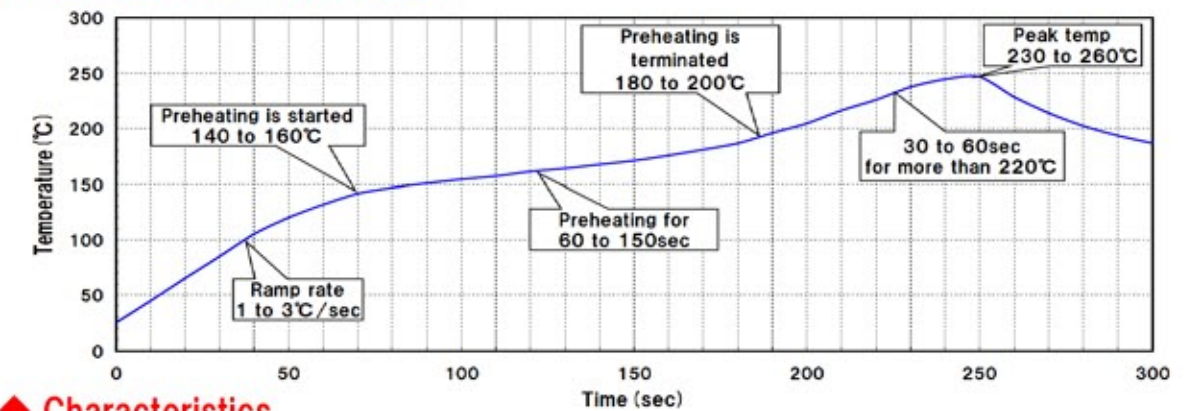
◆ Stable Viscosity even at 24hour Consecutive Printing



◆ Fine Cleanability with Various Detergents



◆ Recommended Peak Profile



◆ Characteristics

Item	Characteristic	Test Method
Alloy Composition	Sn-3.0Ag-0.5Cu	-
Particle Size	20~38 μ m	-
Flux Content	11.5%	JIS Z 3197
Flux identification	ROLO	IPC-J-STD-004
Halide Content	0.02%	Compounding Ratio
Viscosity/Ti Value	200Pa·s/0.51	JIS Z 3284

The above figures are representative values, not guaranteed.



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